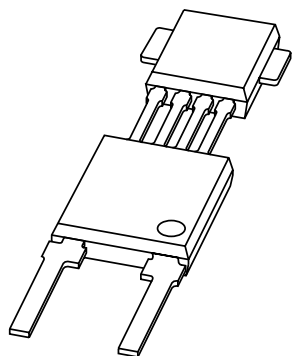


DATA SHEET



KMI20/2

Rotational speed sensor for
extended air gap application

Objective specification

2000 Sep 04

Rotational speed sensor for extended air gap application

KMI20/2

FEATURES

- Digital current output signal
- Digital offset compensation
- Extended air gap
- Zero speed capability
- Wide temperature range
- High tolerance to vibration
- EMC resistant
- Tolerant to positioning.

DESCRIPTION

The KMI20/2 sensor detects rotational speed of magnetized targets⁽¹⁾.

The sensor consists of a magnetoresistive sensor element, a driver IC in BIMOS technology, a digital signal conditioning IC in highly integrated CMOS technology and a ferrite magnet. The frequency of the digital current output signal is proportional to the rotational speed of a magnetized wheel.

CAUTION
Do not press two or more products together against their magnetic forces.

(1) The sensor contains customized integrated circuits. Usage in hydraulic brake systems and in systems with active brake control is forbidden. For all other applications, higher temperature versions of up to 150 °C are available on request.

PINNING

PIN	SYMBOL
1	V _{CC}
2	V-

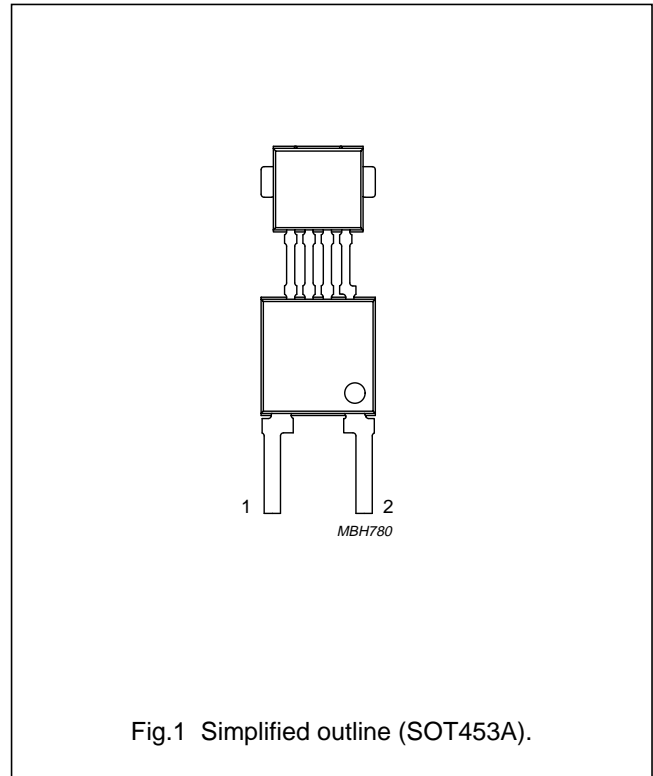


Fig.1 Simplified outline (SOT453A).

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V _{CC}	DC supply voltage	0	12	18	V
I _{CC (low)}	current output signal low	5.6	7	8.4	mA
I _{CC (high)}	current output signal high	11.2	14	16.8	mA
f _t	operating tooth frequency	0	–	2500	Hz
T _{amb}	ambient operating temperature	–40	–	+85	°C

Rotational speed sensor for extended air gap application

KMI20/2

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CC}	DC supply voltage	$T_{amb} = -40$ to $+85$ °C; $R_L = 115$ Ω	0	18	V
T_{stg}	storage temperature		-65	+150	°C
T_{amb}	operating ambient temperature		-40	+85	°C
T_{sld}	soldering temperature	$t < 10$ s	–	260	°C
	output short-circuit duration to GND	see Fig.7	continuous		
	wrong polarity	$T_{amb} = -40$ to $+65$ °C, $R_L = 115$ Ω; note 1	continuous		

Note

1. With $R_L = 115$ Ω the device is continuously protected against wrong polarity of the DC supply voltage (V_{CC}) to GND; see Fig.7.

CHARACTERISTICS

$T_{amb} = 25$ °C; $V_{CC} = 12$ V; test circuit; see Fig.7; $R_L = 115$ Ω; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{CC (low)}$	current output low	-40 to +85 °C; see Fig.6	5.6	7	8.4	mA
$I_{CC (high)}$	current output high	-40 to +85 °C; see Fig.6	11.2	14	16.8	mA
t_r	output signal rise time	$C_L = 100$ pF; 10% to 90% value; see Fig.8	–	0.5	–	μs
t_f	output signal fall time	$C_L = 100$ pF; 90% to 10% value; see Fig.8	–	0.5	–	μs
f_t	operating tooth frequency	for both rotational directions	0	–	2500	Hz
$H_{yin 0 Hz}$	magnetic hysteresis in initial mode	peak to peak	0.2	0.3	0.4	kA/m
$H_{yin(off)}$	magnetic offset in initial mode		-0.2	0	+0.2	kA/m
$H_{y(act)}$	magnetic hysteresis in active mode	percentage of last signal amplitude	30	–	45	%

Rotational speed sensor for extended air gap application

KMI20/2

FUNCTIONAL DESCRIPTION

The KMI20/2 is sensitive to magnetic fields. The functional principle is shown in Fig.3. The field lines of a magnetized target are shown as a straight target (it could also be circular e.g. for rotational speed measurement). The sensor is switched by the magnetic field components $H_{s_{LH}}$ or $H_{s_{HL}}$ either to low (7 mA) or to high (14 mA). Oscillation of the sensor is avoided by the implementation of a hysteresis in the signal conditioning circuit. Stability is ensured by the inclusion of a permanent magnet, the continuous magnetic field of which prevents frequency doubling in the sensor.

The KMI20/2 contains a magnetoresistive sensor element and two ICs: a Position Detector IC (PDIC) and a Line Driver IC (LDIC). The sensor signal is fed into the PDIC. The PDIC is the signal conditioning IC which includes A/D and D/A converters and a Schmitt trigger, and provides digital compensation. The LDIC contains two current sources (one constant and one switchable) and a voltage control unit (see Fig.4).

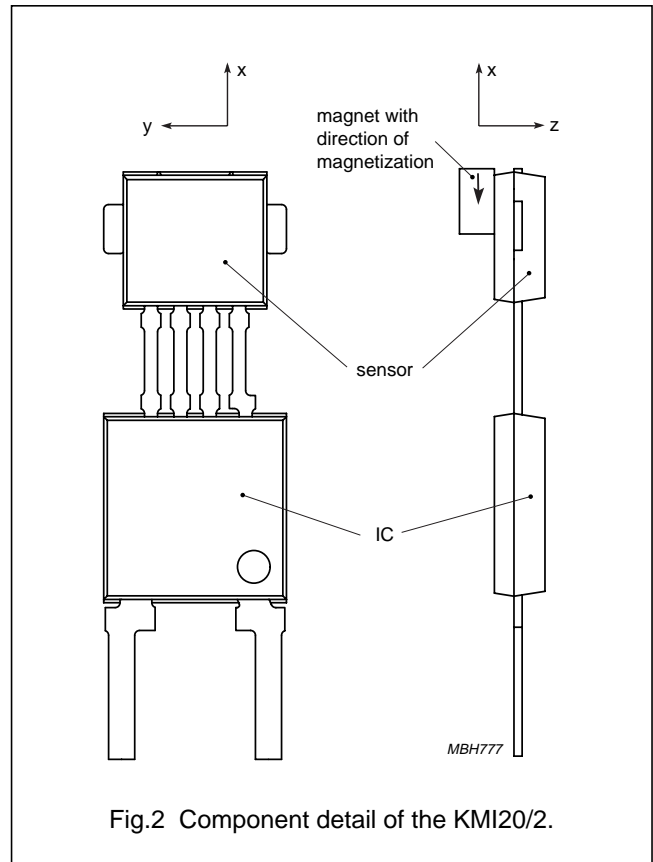


Fig.2 Component detail of the KMI20/2.

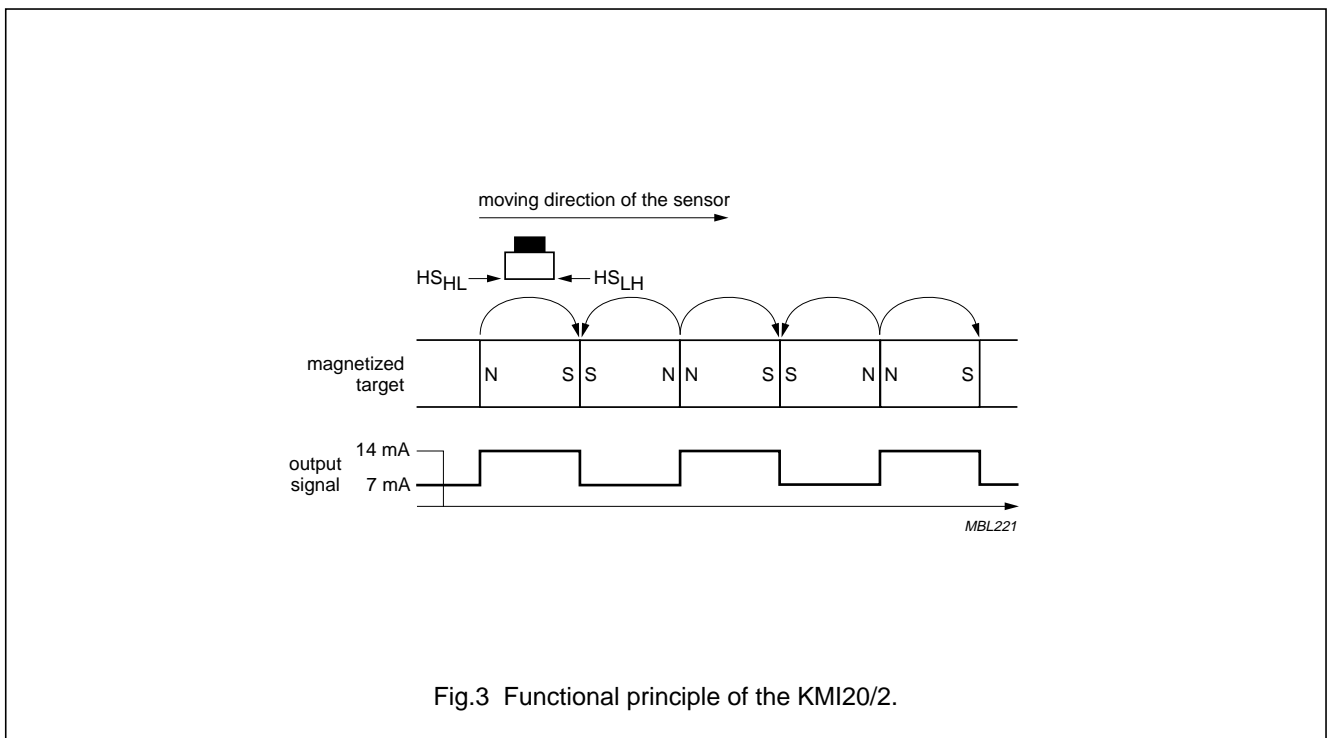


Fig.3 Functional principle of the KMI20/2.

Rotational speed sensor for extended air gap application

KMI20/2

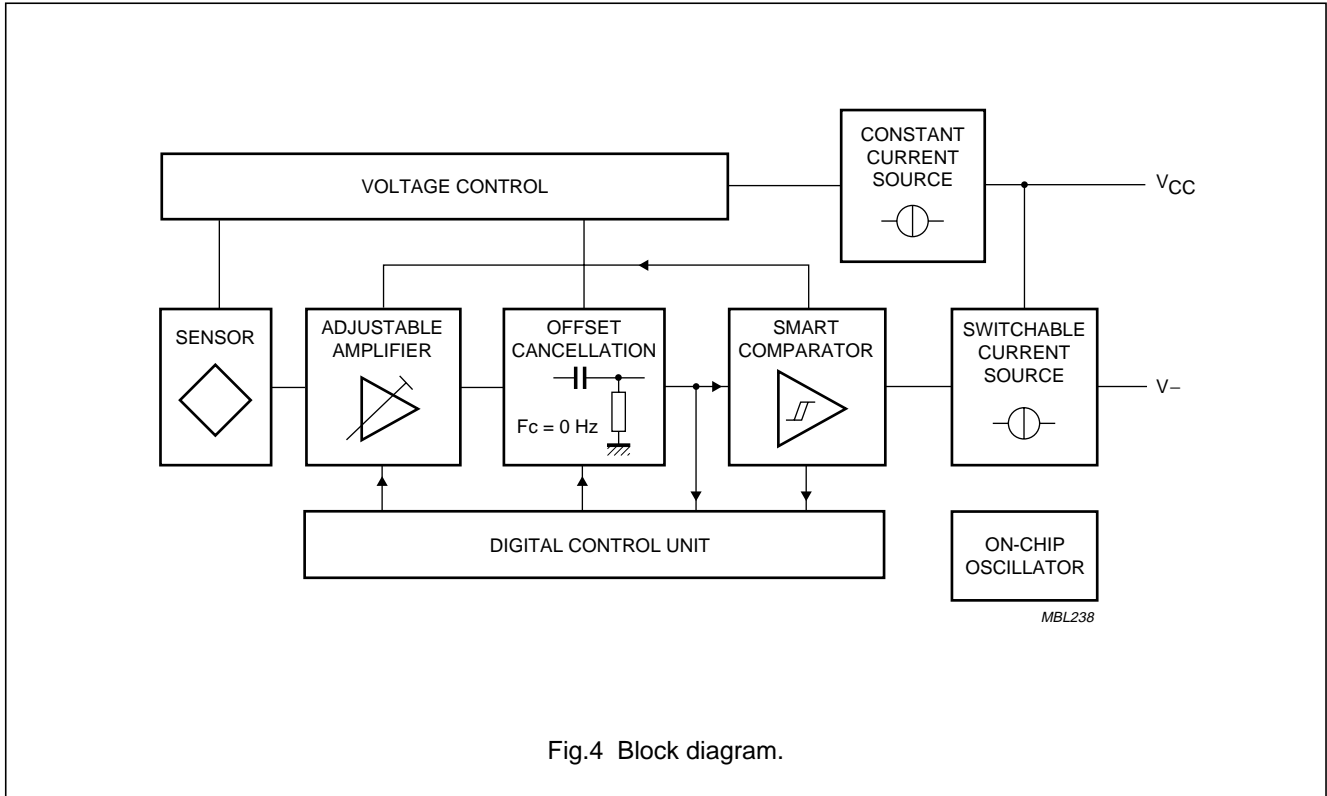


Fig.4 Block diagram.

Figure 5 shows the digital compensation function in algorithmic format. After power-on the sensor system is running in INITIAL MODE 0 Hz. The sensor signal is preamplified but not offset compensated. The output signal represents the specified magnetic field strength (see Chapter “Characteristics”), totally speed independent. When there is a magnetic offset the system must first detect the sensor signal amplitudes to compensate for it (INITIAL_MODE_1_Hz). An output signal is produced (first compensation run finished) at the latest after 11 magnetic field pairs with a frequency above 1 Hz have been sensed.

After detecting the fields in initial mode the PDIC changes to ACTIVE MODE. The sensor signal is permanently offset compensated. The hysteresis is now directly dependent on the last magnetic amplitude (30% to 45%, see Chapter “Characteristics”) down to typically 50 A/m. Quitting ACTIVE MODE is caused by power off or by decreasing the magnetic field frequency below 1 Hz. The system is locked into COMPENSATION MODE and continues to detect every magnetic field down to zero speed.

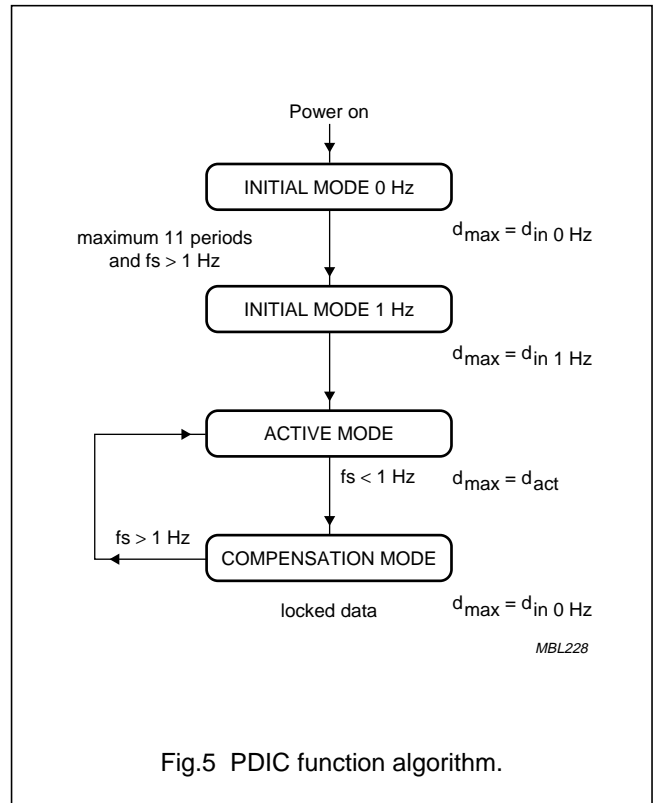
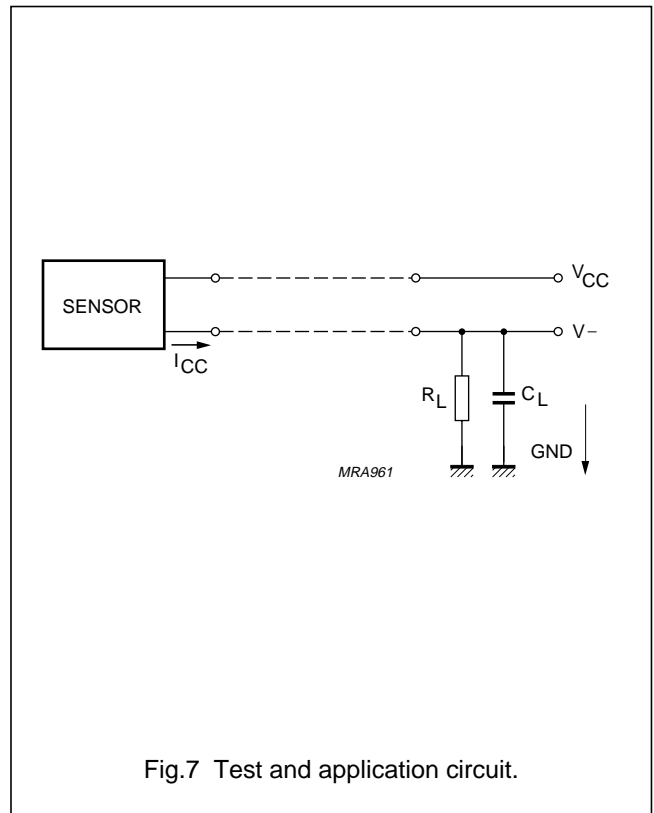
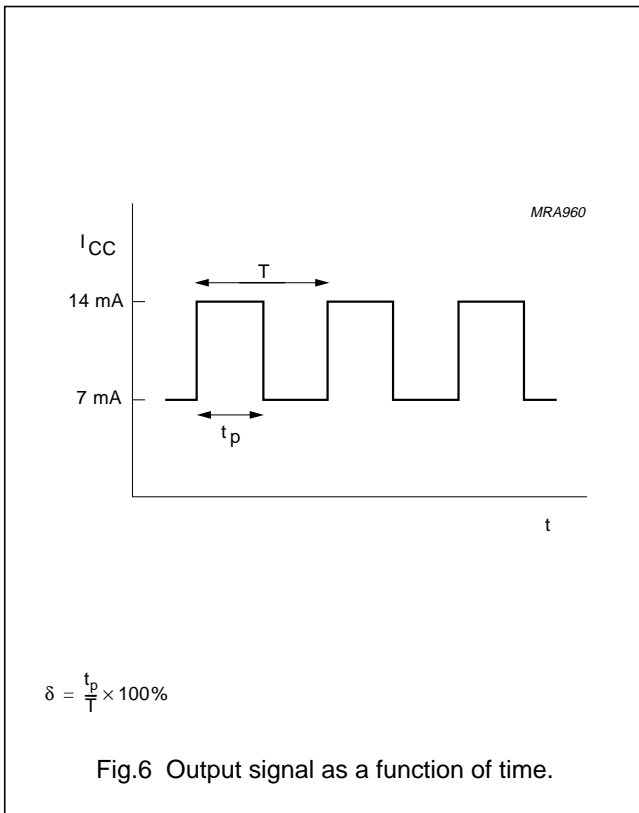


Fig.5 PDIC function algorithm.

Rotational speed sensor for extended air gap application

KMI20/2



Rotational speed sensor for extended air gap application

KMI20/2

EMC

Figure 8 shows a recommended application circuit for automotive applications. It provides a protection interface to meet Electromagnetic Compatibility (EMC) standards and safeguard against voltage spikes. Table 1 lists the tests which are applicable to this circuit and the achieved class of functional status. Protection against 'load dump' (test pulses 5 according to "DIN 40839") means a very high demand on the protection circuit and requires a suitable suppressor diode with sufficient energy absorption capability.

The board net often contains a central load dump protection that makes such a device in the protection circuit of the sensor module unnecessary.

Tests for Electrostatic Discharge (ESD) were conducted in line with "MIL Std. 883D, Method 3015.7" to demonstrate the KMI20/2's handling capabilities. The test conditions were: C = 150 pF, R = 150 Ω and V = 4 kV.

Electromagnetic disturbances with fields up to 150 V/m and f = 1 GHz (ref. "DIN 40839") have no influence on performance.

Table 1 EMC test results

EMC REF. DIN 40839	SYMBOL	MIN. (V)	MAX. (V)	REMARKS	CLASS
Test pulse 1	V _{LD}	-100	-	t _d = 2 ms	C
Test pulse 2	V _{LD}	-	100	t _d = 0.2 ms	A
Test pulse 3a	V _{LD}	-150	-	t _d = 0.1 μs	A
Test pulse 3b	V _{LD}	-	100	t _d = 0.1 μs	A
Test pulse 4	V _{LD}	-7	-	t _d = 130 ms	B
Test pulse 5	V _{LD}	-	120	t _d = 400 ms	B

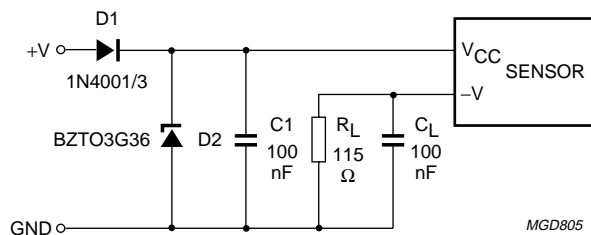


Fig.8 Test/application circuit for the KMI20/2.

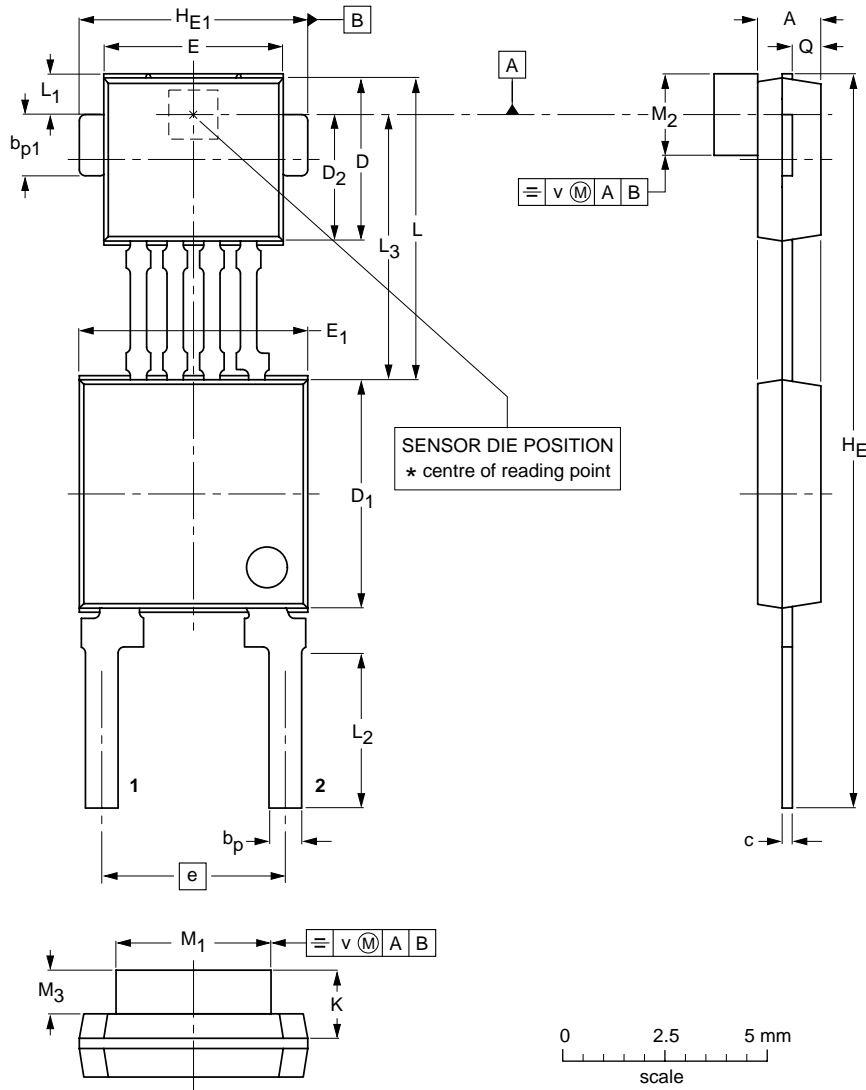
Rotational speed sensor for extended air gap application

KMI20/2

PACKAGE OUTLINE

Plastic single-ended multi-chip package;
magnetized ferrite magnet (3.8 x 2 x 0.8 mm); 4 interconnections; 2 in-line leads

SOT453A



DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾	b _p	b _{p1}	c	D ⁽²⁾	D ₁ ⁽²⁾	D ₂ ⁽²⁾	E ⁽²⁾	E ₁ ⁽²⁾	e	H _E	H _{E1}	K _{max.}	L	L ₁	L ₂	L ₃	M ₁	M ₂	M ₃ ⁽¹⁾	Q	v
mm	1.7 1.4	0.8 0.7	1.57 1.47	0.3 0.24	4.1 3.9	5.7 5.5	3.15 2.95	4.5 4.3	5.7 5.5	4.6 4.4	18.2 17.8	5.6 5.5	1.67	7.55 7.25	1.2 0.9	3.9 3.5	6.55 6.35	3.9 3.7	2.1 1.9	0.9 0.7	0.75 0.65	0.25

Notes

1. Glue thickness not included.
2. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT453A						99-09-22- 00-08-31

Rotational speed sensor for extended air gap application

KMI20/2

DATA SHEET STATUS

DATA SHEET STATUS	PRODUCT STATUS	DEFINITIONS ⁽¹⁾
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

Note

1. Please consult the most recently issued data sheet before initiating or completing a design.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

DISCLAIMERS

Life support applications — These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

Right to make changes — Philips Semiconductors reserves the right to make changes, without notice, in the products, including circuits, standard cells, and/or software, described or contained herein in order to improve design and/or performance. Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no licence or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.

Rotational speed sensor for
extended air gap application

KMI20/2

NOTES

Rotational speed sensor for
extended air gap application

KMI20/2

NOTES

Philips Semiconductors – a worldwide company

Argentina: see South America

Australia: 3 Figtree Drive, HOMEBUSH, NSW 2140,
Tel. +61 2 9704 8141, Fax. +61 2 9704 8139

Austria: Computerstr. 6, A-1101 WIEN, P.O. Box 213,
Tel. +43 1 60 101 1248, Fax. +43 1 60 101 1210

Belarus: Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6,
220050 MINSK, Tel. +375 172 20 0733, Fax. +375 172 20 0773

Belgium: see The Netherlands

Brazil: see South America

Bulgaria: Philips Bulgaria Ltd., Energoproject, 15th floor,
51 James Bourchier Blvd., 1407 SOFIA,
Tel. +359 2 68 9211, Fax. +359 2 68 9102

Canada: PHILIPS SEMICONDUCTORS/COMPONENTS,
Tel. +1 800 234 7381, Fax. +1 800 943 0087

China/Hong Kong: 501 Hong Kong Industrial Technology Centre,
72 Tat Chee Avenue, Kowloon Tong, HONG KONG,
Tel. +852 2319 7888, Fax. +852 2319 7700

Colombia: see South America

Czech Republic: see Austria

Denmark: Sydhavnsgade 23, 1780 COPENHAGEN V,
Tel. +45 33 29 3333, Fax. +45 33 29 3905

Finland: Sinikalliontie 3, FIN-02630 ESPOO,
Tel. +358 9 615 800, Fax. +358 9 6158 0920

France: 51 Rue Carnot, BP317, 92156 SURESNES Cedex,
Tel. +33 1 4099 6161, Fax. +33 1 4099 6427

Germany: Hammerbrookstraße 69, D-20097 HAMBURG,
Tel. +49 40 2353 60, Fax. +49 40 2353 6300

Hungary: see Austria

India: Philips INDIA Ltd, Band Box Building, 2nd floor,
254-D, Dr. Annie Besant Road, Worli, MUMBAI 400 025,
Tel. +91 22 493 8541, Fax. +91 22 493 0966

Indonesia: PT Philips Development Corporation, Semiconductors Division,
Gedung Philips, Jl. Buncit Raya Kav.99-100, JAKARTA 12510,
Tel. +62 21 794 0040 ext. 2501, Fax. +62 21 794 0080

Ireland: Newstead, Clonskeagh, DUBLIN 14,
Tel. +353 1 7640 000, Fax. +353 1 7640 200

Israel: RAPAC Electronics, 7 Kehilat Saloniki St, PO Box 18053,
TEL AVIV 61180, Tel. +972 3 645 0444, Fax. +972 3 649 1007

Italy: PHILIPS SEMICONDUCTORS, Via Casati, 23 - 20052 MONZA (MI),
Tel. +39 039 203 6838, Fax +39 039 203 6800

Japan: Philips Bldg 13-37, Kohnan 2-chome, Minato-ku,
TOKYO 108-8507, Tel. +81 3 3740 5130, Fax. +81 3 3740 5057

Korea: Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL,
Tel. +82 2 709 1412, Fax. +82 2 709 1415

Malaysia: No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR,
Tel. +60 3 750 5214, Fax. +60 3 757 4880

Mexico: 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905,
Tel. +9-5 800 234 7381, Fax +9-5 800 943 0087

Middle East: see Italy

Netherlands: Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB,
Tel. +31 40 27 82785, Fax. +31 40 27 88399

New Zealand: 2 Wagener Place, C.P.O. Box 1041, AUCKLAND,
Tel. +64 9 849 4160, Fax. +64 9 849 7811

Norway: Box 1, Manglerud 0612, OSLO,
Tel. +47 22 74 8000, Fax. +47 22 74 8341

Pakistan: see Singapore

Philippines: Philips Semiconductors Philippines Inc.,
106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI,
Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474

Poland: Al.Jerozolimskie 195 B, 02-222 WARSAW,
Tel. +48 22 5710 000, Fax. +48 22 5710 001

Portugal: see Spain

Romania: see Italy

Russia: Philips Russia, Ul. Usatcheva 35A, 119048 MOSCOW,
Tel. +7 095 755 6918, Fax. +7 095 755 6919

Singapore: Lorong 1, Toa Payoh, SINGAPORE 319762,
Tel. +65 350 2538, Fax. +65 251 6500

Slovakia: see Austria

Slovenia: see Italy

South Africa: S.A. PHILIPS Pty Ltd., 195-215 Main Road Martindale,
2092 JOHANNESBURG, P.O. Box 58088 Newville 2114,
Tel. +27 11 471 5401, Fax. +27 11 471 5398

South America: Al. Vicente Pinzon, 173, 6th floor,
04547-130 SÃO PAULO, SP, Brazil,
Tel. +55 11 821 2333, Fax. +55 11 821 2382

Spain: Balmes 22, 08007 BARCELONA,
Tel. +34 93 301 6312, Fax. +34 93 301 4107

Sweden: Kottbygatan 7, Akalla, S-16485 STOCKHOLM,
Tel. +46 8 5985 2000, Fax. +46 8 5985 2745

Switzerland: Allmendstrasse 140, CH-8027 ZÜRICH,
Tel. +41 1 488 2741 Fax. +41 1 488 3263

Taiwan: Philips Semiconductors, 5F, No. 96, Chien Kuo N. Rd., Sec. 1,
TAIPEI, Taiwan Tel. +886 2 2134 2451, Fax. +886 2 2134 2874

Thailand: PHILIPS ELECTRONICS (THAILAND) Ltd.,
60/14 MOO 11, Bangna Trad Road KM. 3, Bagna, BANGKOK 10260,
Tel. +66 2 361 7910, Fax. +66 2 398 3447

Turkey: Yukari Dudullu, Org. San. Blg., 2.Cad. Nr. 28 81260 Umraniye,
ISTANBUL, Tel. +90 216 522 1500, Fax. +90 216 522 1813

Ukraine: PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7,
252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461

United Kingdom: Philips Semiconductors Ltd., 276 Bath Road, Hayes,
MIDDLESEX UB3 5BX, Tel. +44 208 730 5000, Fax. +44 208 754 8421

United States: 811 East Arques Avenue, SUNNYVALE, CA 94088-3409,
Tel. +1 800 234 7381, Fax. +1 800 943 0087

Uruguay: see South America

Vietnam: see Singapore

Yugoslavia: PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD,
Tel. +381 11 3341 299, Fax.+381 11 3342 553

For all other countries apply to: Philips Semiconductors,
Marketing Communications, Building BE-p, P.O. Box 218, 5600 MD EINDHOVEN,
The Netherlands, Fax. +31 40 27 24825

Internet: <http://www.semiconductors.philips.com>

© Philips Electronics N.V. 2000

SCA 70

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Printed in The Netherlands

613520/01/pp12

Date of release: 2000 Sep 04

Document order number: 9397 750 07237

Let's make things better.

**Philips
Semiconductors**



PHILIPS